

650V Super-Junction Power MOSFET

FEATURES

- Very low FOM $R_{DS(on)} \times Q_g$
- 100% avalanche tested
- RoHS compliant

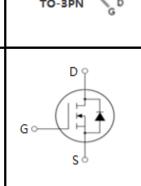
APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

TO-220 GDS	TO-220F GDS	TO-BPN GD
		Dq

RoHS

Device Marking and Package Information				
Device	Package	Marking		
TPP65R170M	TO-220	65R170M		
TPA65R170M	TO-220F	65R170M		
TPV65R170M	TO-3PN	65R170M		



Absolute Maximum Ratings $T_c = 25^{\circ}C$, unless otherwise noted					
Deservator	Cumhal	Value			11
Parameter	Symbol	TO-220	TO-3PN	TO-220F	Unit
Drain-Source Voltage (V _{GS} = 0V)	V _{DSS}		650		V
Continuous Drain Current	I _D	20		А	
Pulsed Drain Current (note1)	I _{DM}	60		А	
Gate-Source Voltage	V _{GSS}	±30		V	
Single Pulse Avalanche Energy (note2)	E _{AS}	484		mJ	
Avalanche Current (note1)	I _{AR}	3.5		А	
Repetitive Avalanche Energy (note1)	E _{AR}	0.7		mJ	
Power Dissipation (T _C = 25ºC)	P _D	151 34		W	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55~+150		°C	

Thermal Resistance					
Desemptor	Cumb al	Value			11
Parameter	Symbol	TO-220	TO-3PN	TO-220F	Unit
Thermal Resistance, Junction-to-Case	R _{thJC}	0.83		3.7	00.000
Thermal Resistance, Junction-to-Ambient	R _{thJA}	62 80		80	°C/W



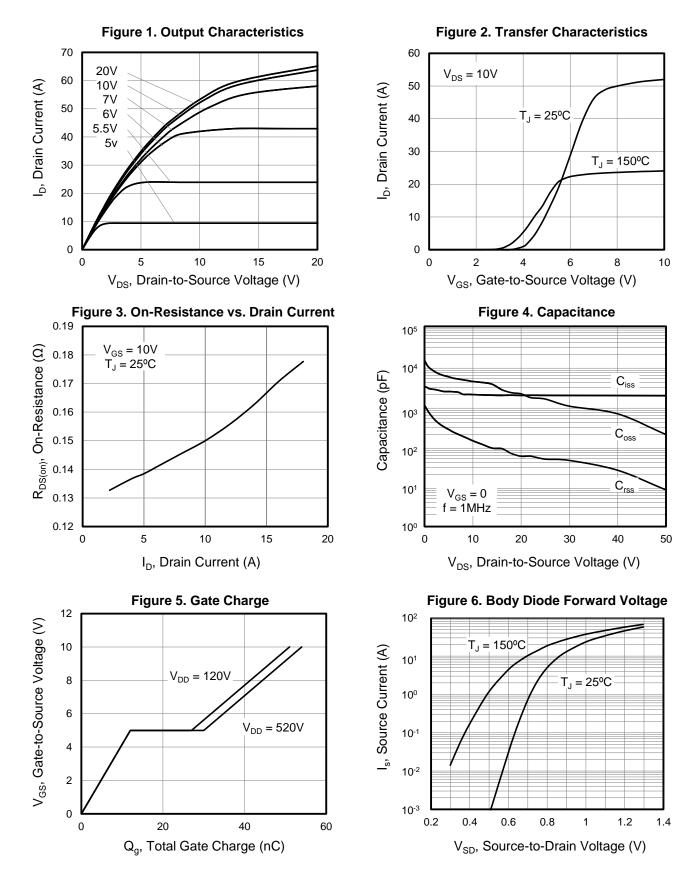
Devenueden			Value				
Parameter	Symbol Test Conditions		Min.	Тур.	Max.	Unit	
Static		•					
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_{D} = 250 \mu A$	650			V	
		$V_{DS} = 650V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 650V, V _{GS} = 0V, T _J = 150°C			100	- μΑ	
Gate-Source Leakage	I _{GSS}	$V_{GS} = \pm 30 V$			±100	nA	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2.5		4.0	V	
Drain-Source On-Resistance (Note3)	$R_{DS(on)}$	V _{GS} = 10V, I _D = 10A		0.15	0.17	Ω	
Forward Transconductance (Note3)	g _{fs}	V _{DS} = 10V, I _D = 10A		23		S	
Dynamic		•					
Input Capacitance	C _{iss}	$\gamma = 0 \gamma$		1840			
Output Capacitance	C _{oss}	$V_{GS} = 0V,$ $V_{DS} = 50V,$		197		pF	
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		8			
Total Gate Charge	Q _g			54		nC	
Gate-Source Charge	Q _{gs}	$V_{DD} = 520V, I_{D} = 20A, V_{GS} = 10V$		12			
Gate-Drain Charge	Q_{gd}			18			
Turn-on Delay Time	t _{d(on)}			66			
Turn-on Rise Time	t _r	V _{DD} = 400V, I _D = 20A,		27			
Turn-off Delay Time	t _{d(off)}	$R_{G} = 25\Omega$		167		ns	
Turn-off Fall Time	t _f			21			
Drain-Source Body Diode Characteris	stics	· · · ·					
Continuous Body Diode Current	I _S	T 0500			20		
Pulsed Diode Forward Current	I _{SM}	T _C = 25°C			60	A	
Body Diode Voltage	V_{SD}	$T_J = 25^{\circ}C, I_{SD} = 20A, V_{GS} = 0V$		0.9	1.2	V	
Reverse Recovery Time	t _{rr}			336		ns	
Reverse Recovery Charge	Q _{rr}	V _R = 480V, I _F = I _S , di _F /dt = 100A/µs		3.4		μC	
Peak Reverse Recovery Current	l _{rrm}			20		А	

Notes

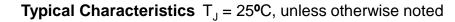
- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2. I_{AS} = 3.5A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25°C
- 3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 1%

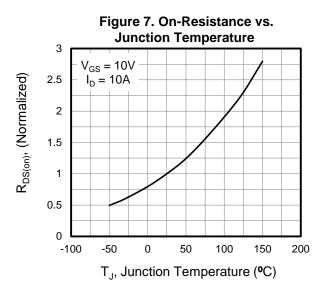


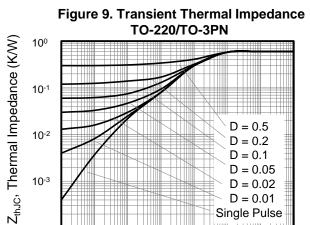
Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted











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T_p, Pulse Width (s)

10-3

D = 0.01

10-1

10⁰

Single Pulse

10-2

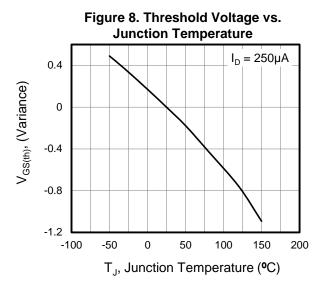
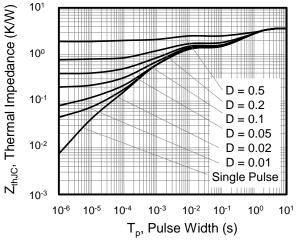


Figure 10. Transient Thermal Impedance TO-220F



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10-5





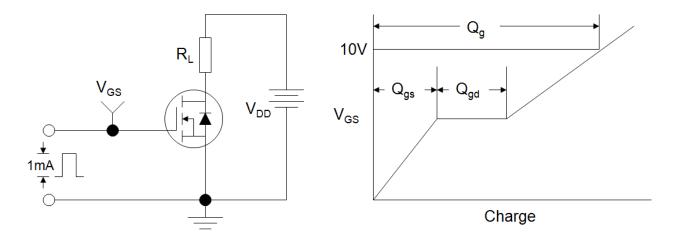


Figure B: Resistive Switching Test Circuit and Waveform

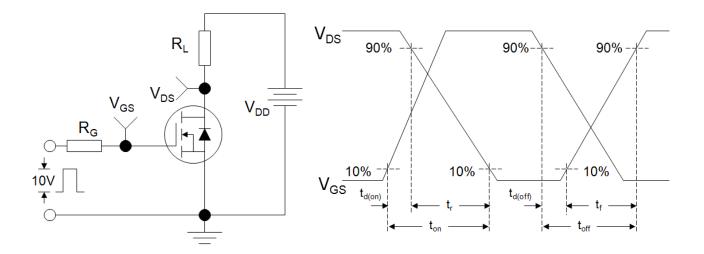
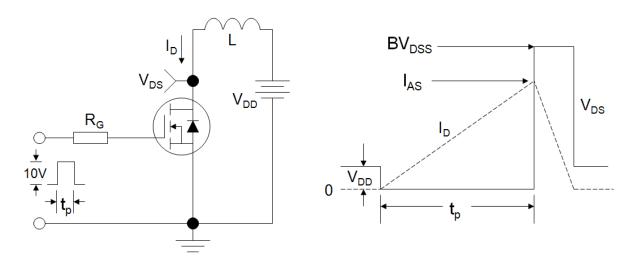


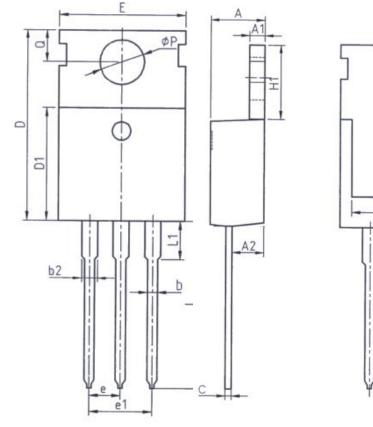
Figure C: Unclamped Inductive Switching Test Circuit and Waveform

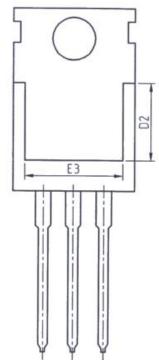


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TO-220



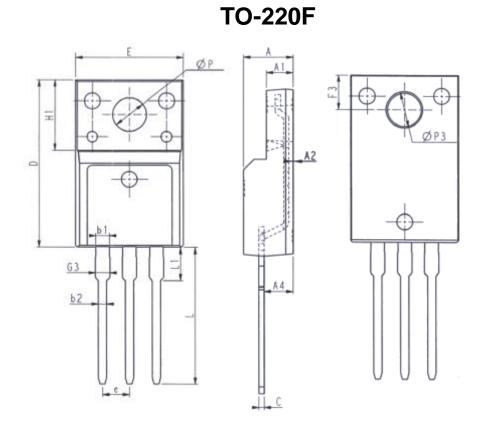


Unit: mm				
Symbol	Min.	Max.		
Α	4. 37	4.77		
A1	1.25	1.45		
A2	2.20	2.60		
b	0.70	0.95		
b2	1.17	1.47		
С	0.40	0.65		
D	15. 10	16. 10		
D1	8.80	9.40		
D2	5.50	-		

Unit: mm				
Symbol	Min. Max.			
E	9.70	10. 30		
E3	7.00	-		
e	2. 54BSC			
e1	5. 08BSC			
H1	6. 25	6.85		
L	12.75	13.80		
L1	-	3. 40		
Р	3. 40	3.80		
Q	2.60	3.00		

E

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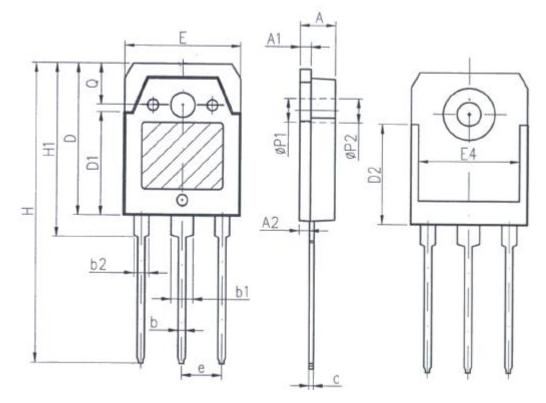


Unit: mm			Unit: mm		
Symbol	Min.	Max.	Symbol	Min.	Max.
E	9.96	10.36	L	12.68	13. 28
Α	4.50	4.90	L1	2.93	3.13
A1	2.34	2.74	Р	3.03	3.38
A2	0.30	0.60	P3	3.15	3.65
A4	2.56	2.96	F3	3.15	3.45
с	0.40	0.65	G3	1.25	1.55
D	15. 57	16. 17	b1	1.18	1.43
H1	6. 70REF		b2	0.70	0.95
e	2. 54BSC				

V1.0



TO-3PN



Unit:mm				
Symbol	Min.	Max.		
Α	4.6	5		
A1	1.4	1.65		
A2	1.18	1. 58		
b	0.8	1.2		
b 1	2.8	3. 2		
b2	1.8	2.2		
c	0.5	0.75		
D	19.6	20.2		
D1	13.55	14. 25		
D2	12. 9	PREF		
E	15.35	15.85		
E4	12.6	-		
е	5. 45TYP			
Н	40.1	40.9		
H1	23.15	23.65		
P1	3. 2REF			
P2	3. 5REF			



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